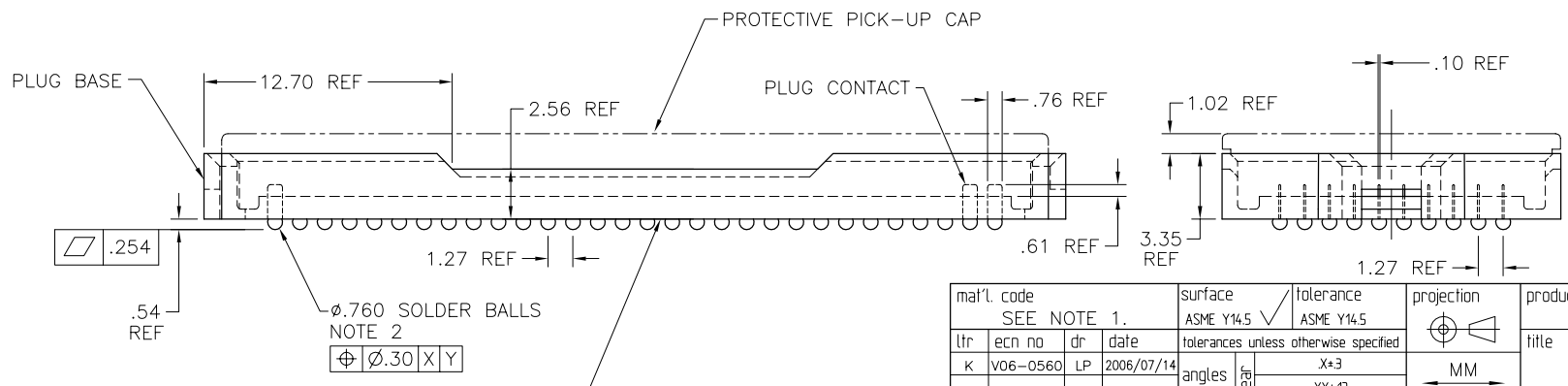
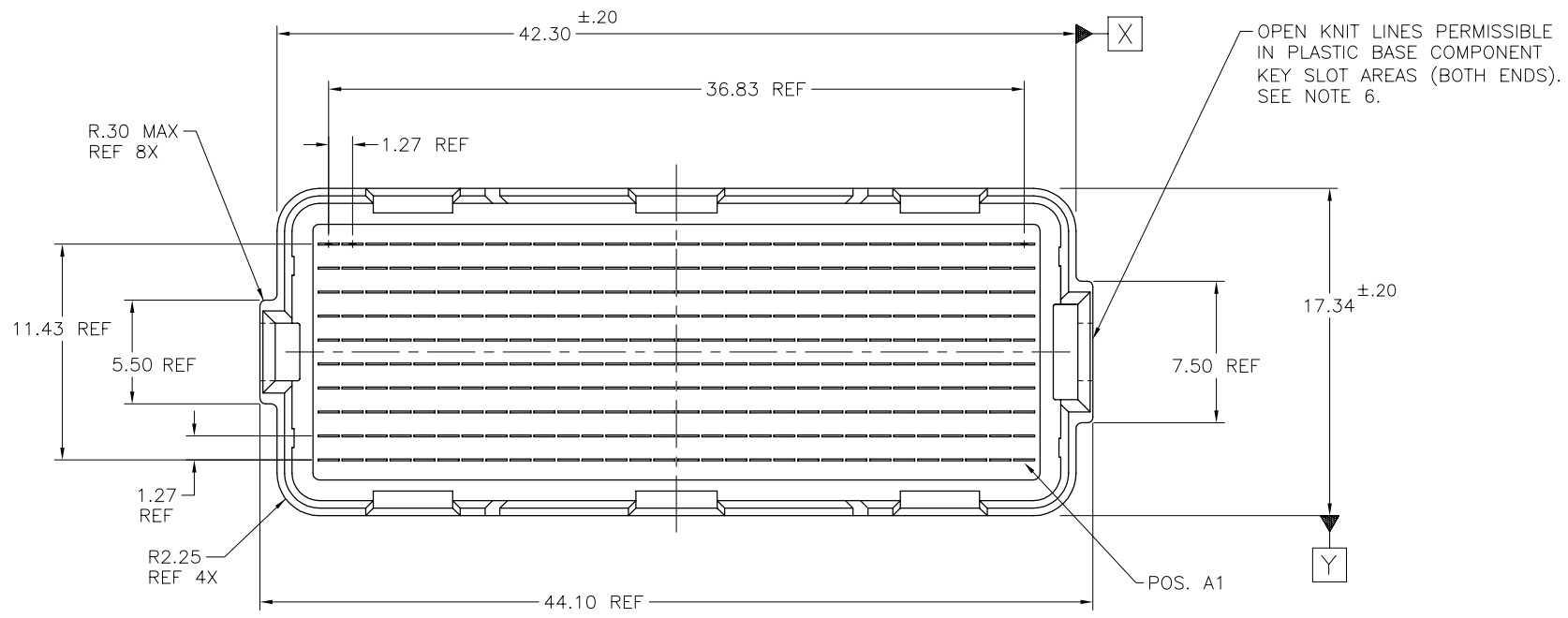




1 | 2

3

4



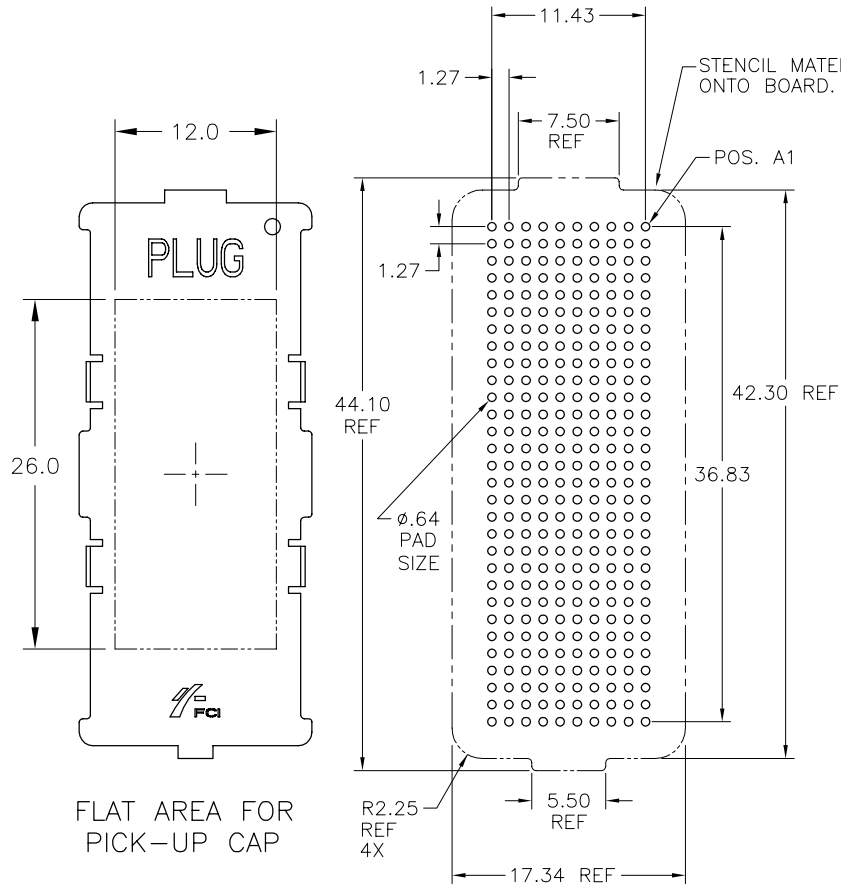
mat'l code	SEE NOTE 1.	surface	ASME Y14.5 ✓	tolerance	ASME Y14.5	projection	product family	MEG-ARRAY
ltr	ec'n no	dr	date	tolerances unless otherwise specified		MM	title	
K	V06-0560	LP	2006/07/14	angles	X+3	MM	0mm PLUG ASSY	
-	-	-	-	line fit	.XX+13	scale	10 X 30 = 300 POS.	
E	V10232	DRW	6/14/01	0° ±2'	XXX+051	3:1	sheet 1 of 3	
F	V20006	DRW	1/7/02	dr	D.WAUGHEN	12.16.98	size	
G	V20692	DRW	4/9/02	enfr	D.HARPER	12.16.98	A4	
H	V03-0680	DAI	6/19/03	chr	D.HARPER	12.16.98	type	
J	V04-0940	VS	10/18/01	appd	D.HARPER	12.16.98	CUSTOMER Drawing	
sheet index	revision sheet	K	K	K				
		1	2	3				

1

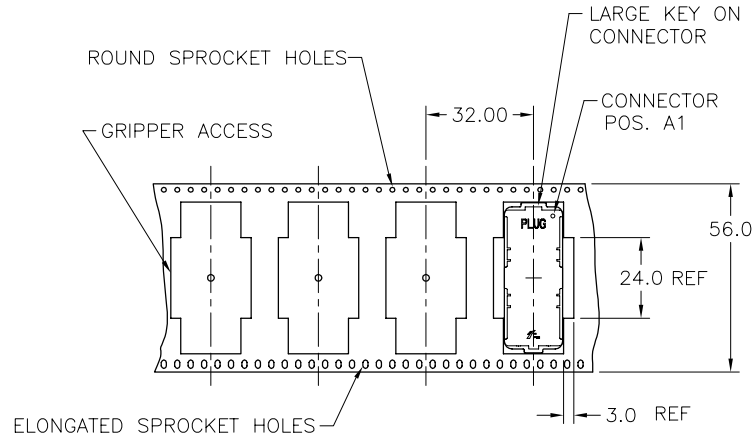
2

3

4



BOARD PATTERN



TAPE & REEL PACKAGING SCALE: NONE
PER EIA 481-3

mat'l. code SEE NOTE 1.		surface ASME Y14.5 ✓		tolerance ASME Y14.5		projection ⊕		product family MEG-ARRAY	
ltr	ecr no	dr	date	tolerances unless otherwise specified					
k				angles	XX*13	XX*3	MM		title 0mm PLUG ASSY 10 X 30 = 300 POS.
				0° ±2'	XXX*051	XXX*051	scale 2:1		
		dr	D.WAUGHEN	12.16.98			FCI		dwg no
		enr	D.HARPER	12.16.98					sheet 2 of 3
		chr	D.HARPER	12.16.98					84500
		appd	D.HARPER	12.16.98					size A4
sheet index		revision sheet		type CUSTOMER Drawing					

PRODUCT NUMBER	PICK-UP CAP	CONTACT PLATING	SOLDER BALL
84500-002	YES	15u" (.38um) Au OVER Ni	SnPb
84500-002LF			SnAgCu LEAD FREE ⑦⑧
84500-102	YES	30u" (.76um) Au OVER Ni	SnPb
84500-102LF			SnAgCu LEAD FREE ⑦⑧
84500-202	YES	SEE MATED HEIGHT TABLE (BELOW).	SnPb
84500-202LF			SnAgCu LEAD FREE ⑦⑧

NOTES:

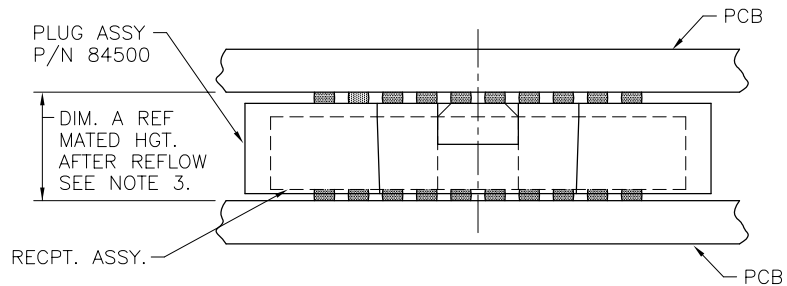
① MAT'L

HOUSING: LCP
CONTACT: COPPER ALLOY

PLATING

CONTACT: (SEE TABLE ON SHEET3)
SOLDER BALL: (SEE TABLE ON SHEET3)
EUTECTIC SnPb OR LEAD FREE
95.5Sn/4Ag/0.5Cu

- ② SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.
- ③ MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.
- ④ PLATING FOR INDICATED -2XX SERIES PART NOS. MEETS THE REQUIREMENTS OF NORTEL NPS25298-2 (CENTRAL OFFICE ENVIRONMENT, 25 YEAR LIFE EXPECTANCY).
- ⑤ PLATING FOR INDICATED -2XX SERIES PART NOS. IS Au OVER Ni WITH SPECIAL CONTACT GEOMETRY TO MEET REQUIREMENTS OF TELCORDIA GR-1217-CORE: CENTRAL OFFICE ENVIRONMENT.
- ⑥ KNIT LINE: SLIGHT VISIBLE MARKS (USUALLY A LINE) INDICATING THE DIRECTION AND MEETING POINT OF PLASTIC RESIN FLOW FRONTS TRAVELING AROUND ANY OBSTRUCTIONS TO THE RESIN FLOW VIA THE REQUIRED MOLD TOOLING.
- ⑦ FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION
- ⑧ THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION



MATED HEIGHT TABLE		
DIM. A	RECPT. ASSY. P/N	-2XX PLATING
4.0	84501	SEE NOTE 4.
5.5	84502	*
8.0	84553	SEE NOTE 5.

* 84502 NOT AVAILABLE IN TELCORDIA/NORTEL VERSION.

MATED HEIGHT AFTER REFLOW IS BASED ON ϕ .64mm PAD (METAL-DEFINED) AND .13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3.

END VIEW - MATED CONNECTORS SCALE: NONE

mat'l. code SEE NOTE 1.		surface ASME Y14.5 ✓	tolerance ASME Y14.5	projection 	product family MEG-ARRAY
ltr	ecn no	dr	date	tolerances unless otherwise specified	title 0mm PLUG ASSY 10 X 30 = 300 POS.
k				angles X*.3 .XX*.13	scale 2:1
				0' ±2'	XXX*.051
		dr	D.WAUGHEN	12.16.98	FCI dwg no 84500 sheet 3 of 3 size A4 type CUSTOMER Drawing
		enr	D.HARPER	12.16.98	
		chr	D.HARPER	12.16.98	
		appd	D.HARPER	12.16.98	
sheet index	revision sheet				